

Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capability specified
- ECOPACK[®]2 compliant component (STPS4045CT)

Description

This dual center tap Schottky rectifier is suited for switchmode power supply and high frequency DC to DC converters.

Packaged in TO-247 or TO-220AB this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

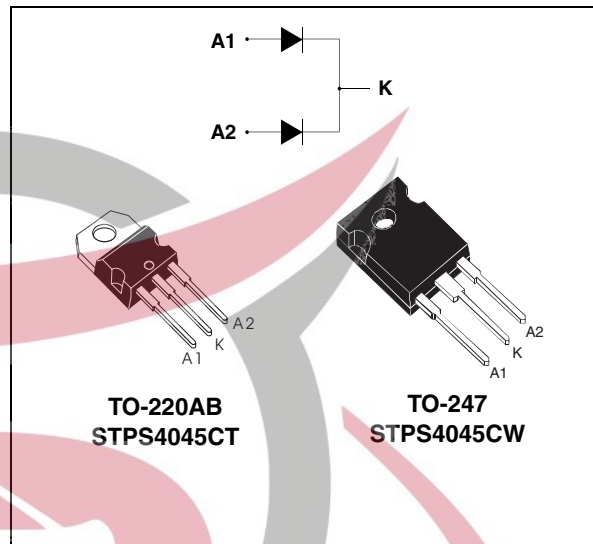


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 20 A
V_{RRM}	45 V
$T_j(max)$	175 °C
$V_F(max)$	0.63 V

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1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

Symbol	Parameter			Value	Unit	
V _{RRM}	Repetitive peak reverse voltage			45	V	
I _{F(RMS)}	Forward rms current			30	A	
I _{F(AV)}	Average forward current	TO-247	T _C = 150 °C, δ = 0.5	Per diode	20	A
			T _C = 145 °C, δ = 0.5	Per device	40	
		TO-220AB	T _C = 145 °C, δ = 0.5	Per diode	20	A
			T _C = 130 °C, δ = 0.5	Per device	40	
I _{FSM}	Surge non repetitive forward current		t _p = 10 ms sinusoidal	220	A	
I _{RRM}	Repetitive peak reverse current		t _p = 2 μs square F=1 kHz	1	A	
I _{RSM}	Non repetitive peak reverse current		t _p = 100 μs square	3	A	
P _{ARM}	Repetitive peak avalanche power		t _p = 1 μs T _j = 25 °C	6000	W	
T _{stg}	Storage temperature range			-65 to + 175	°C	
T _j	Maximum operating junction temperature ⁽¹⁾			175	°C	
dV/dt	Critical rate of rise reverse voltage			10000	V/μs	

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistances

Symbol	Parameter			Value	Unit
R _{th(j-c)}	Junction to case	TO-247	Per diode	1.5	°C/W
			Total	0.8	
		TO-220AB	Per diode	1.8	
			Total	1.3	
R _{th(c)}	Coupling	TO-247	0.1		
		TO-220AB	0.8		

When the diodes 1 and 2 are used simultaneously :
 $\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^\circ\text{C}$	-	-	200	μA
		$T_j = 125\text{ }^\circ\text{C}$	-	11	40	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 25\text{ }^\circ\text{C}$	-	-	0.76	V
		$T_j = 125\text{ }^\circ\text{C}$	-	0.56	0.63	
		$T_j = 25\text{ }^\circ\text{C}$	-	-	0.94	
		$T_j = 125\text{ }^\circ\text{C}$	-	0.7	0.83	

1. Pulse test : $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation :
 $P = 0.43 \times I_{F(AV)} + 0.01 \times I_{F(RMS)}^2$

Figure 1. Average forward power dissipation versus average forward current (per diode)

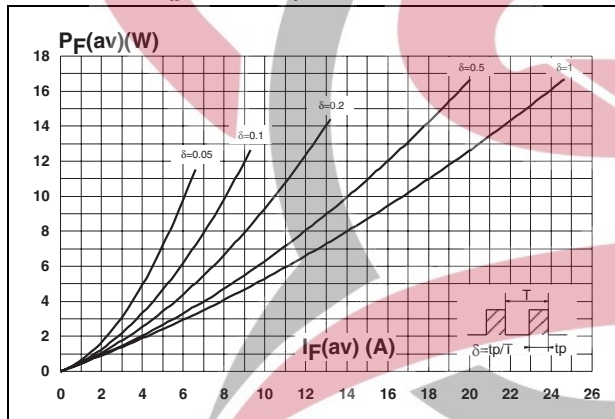


Figure 3. Normalized avalanche power derating versus pulse duration

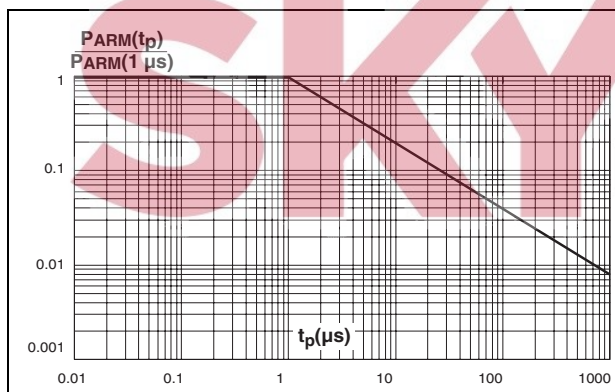


Figure 2. Average forward current versus ambient temperature (delta = 0.5 per diode)

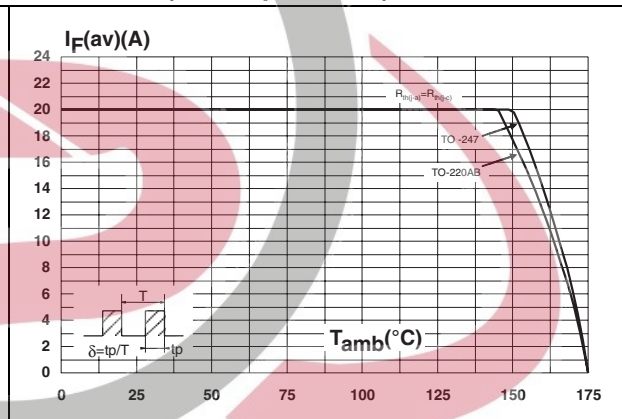


Figure 4. Normalized avalanche power derating versus junction temperature

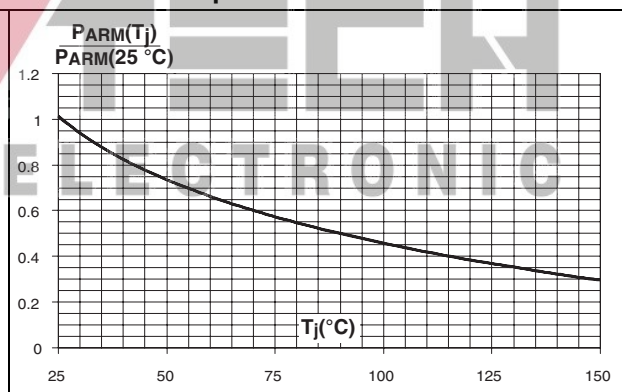


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

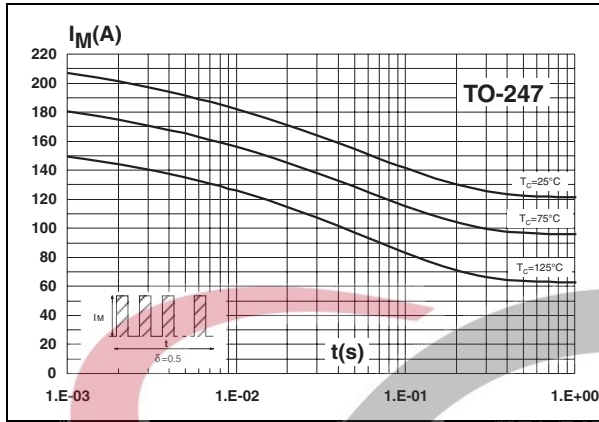


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

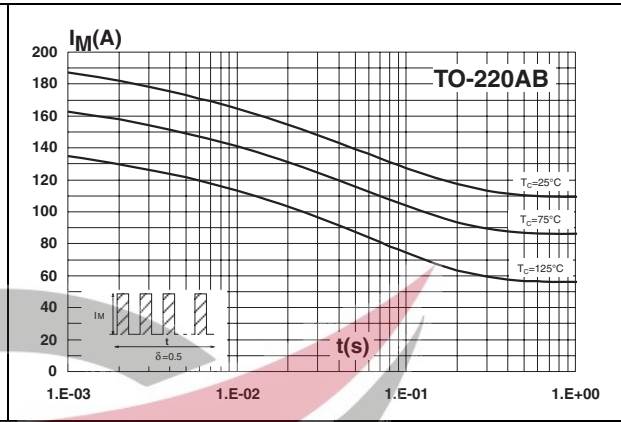


Figure 7. Relative variation of thermal impedance junction to case versus pulse duration

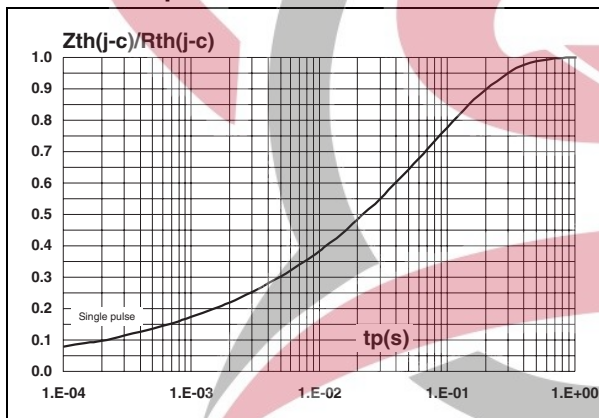


Figure 8. Reverse leakage current versus reverse voltage applied (typical values, per diode)

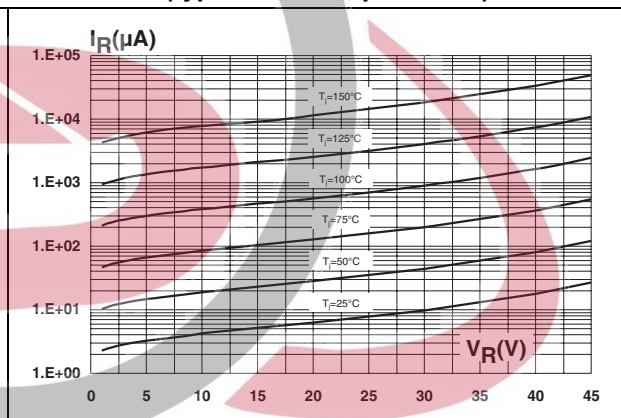


Figure 9. Junction capacitance versus reverse voltage applied (typical values, per diode)

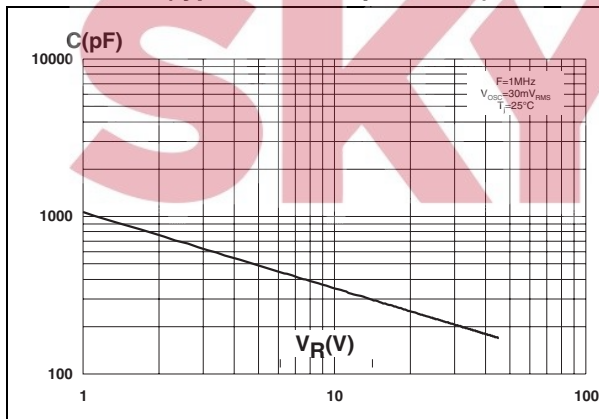
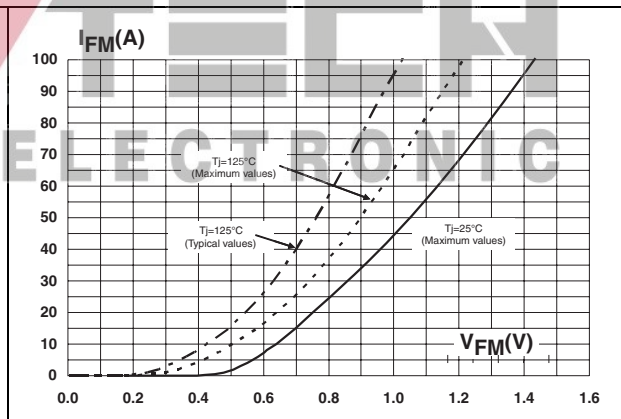


Figure 10. Forward voltage drop versus forward current (per diode)

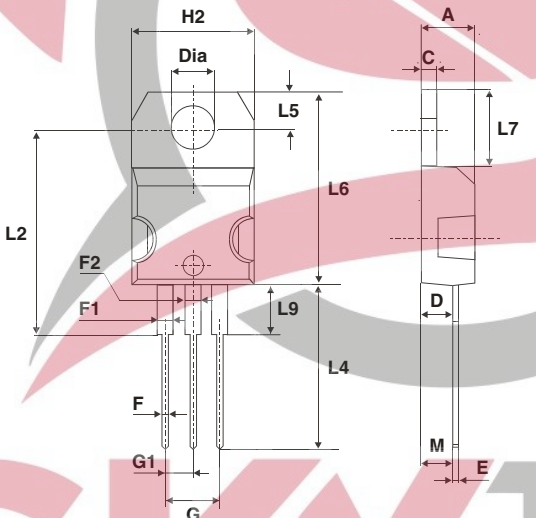


2 Package information

- Epoxy meets UL94,V0
- Cooling method: by conduction (C)
- Recommended torque values: TO-220AB 0.4 to 0.6 N·m, TO-247 0.55 N·m
- Maximum torque value: TO-247 1.0 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. TO-220AB dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

Table 6. TO-247 dimensions

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.16	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F1		3.00			0.118	
F2		2.00			0.079	
F3	1.90		2.40	0.075		0.094
F4	3.00		3.40	0.118		0.134
G		10.90			0.429	
H	15.45		16.03	0.608		0.631
L	19.85		21.09	0.781		0.830
L1	3.70		4.30	0.146		0.169
L2	18.30		19.13	0.720		0.753
L3	14.20		20.30	0.559		0.799
L4	34.05		41.38	1.341		1.629
L5	5.35		6.30	0.211		0.248
M	2.00		3.00	0.079		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.140		0.144



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS4045CW	STPS4045CW	TO-247	4.46 g	30	Tube
STPS4045CT	STPS4045CT	TO-220AB	1.9 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
July-2003	4C	Previous issue.
09-Nov-2009	5	Added TO-220AB package. Removed SOT-93 package.



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